

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	5	(die near pad\$1) AND (suspension near lead\$1) AND (chip die) AND branch\$3 AND end\$1 AND lead\$1 AND ((upper lower side) near (surface\$1 face\$1)) AND (resin seal\$3) AND terminal\$1 AND wir\$3 AND (nearby vicinity) AND corner\$1 AND expos\$3 AND (electrically near connect\$3). CLM.	US-PGPUB; USPAT	OR	ON	2005/10/12 11:42
S1	31556	257/459,676,786,100,433,434,687,767-796, 81,99,666-677.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/04/27 20:21
S2	1	S1 and (end\$1 near2 lead\$1 near2 expos\$3 near2 (side near (surface\$1 face\$1)) near2 (resin seal\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/04/27 20:24
S3	41	S1 and (end\$1 with lead\$1 with expos\$3 with (side near (surface\$1 face\$1)) with (resin seal\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/04/27 20:24
S4	1	(die near pad\$1) with (suspension near lead\$1) with branch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/10/12 11:33
S5	9	(suspension near lead\$1) with branch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/04/28 19:16
S6	34	terminal\$1 with (conduct\$3 near material\$1) with different with lead\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/04/28 19:18